

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Huang, et al.	Docket No.:	TSM03-0176
Serial No.:	TBD	Art Unit:	TBD
Filed:	Herewith	Examiner:	TBD
For:	Hybrid Copper / Low k Dielectric Interconnect Integration Method and Device		

Mail Stop: Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

Preliminary Amendment

Dear Sir:

Please enter the following preliminary amendment prior to examination of the above-referenced patent application filed herewith.

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